

Layers Color Coding



Photoresist layer



Deposited/plated metal layer



Deposited/grown other dielectric layer



Deposited/grown Si₃N₄ layer



Deposited/grown SiO₂ layer



Deposited/grown Si layer



Si <100> n-type

- For each layer a clear label is to be given indicating, as applicable, material, orientation, doping type, resistivity, thickness and mode of material deposition etc.,

Fabrication Flow

Process Step

Cross Section View

Top View/Mask

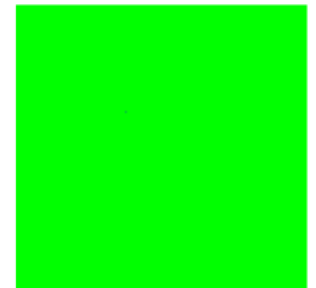
- RCA Cleaning



- SiO₂ growth



- Lithography



Fabrication Flow

Process Step

- Oxide Etch

Cross Section View



- Photo Resist removal



Top View/Mask

PV Fabrication Flow

Process Step

Cross Section View

Top View/Mask

- RCA Clean



- Doping



- Anti Reflection coating



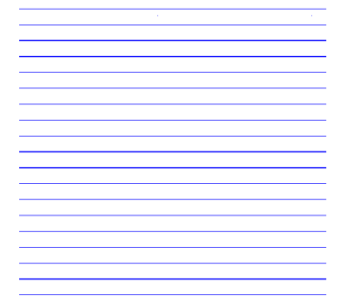
PV Fabrication Flow

Process Step

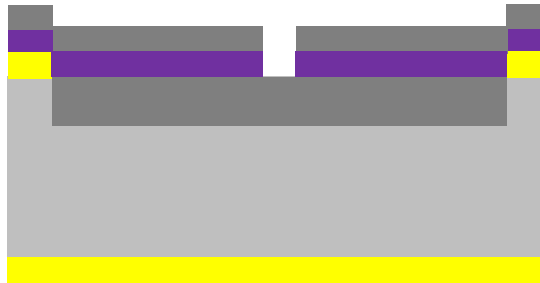
Cross Section View

Top View/Mask

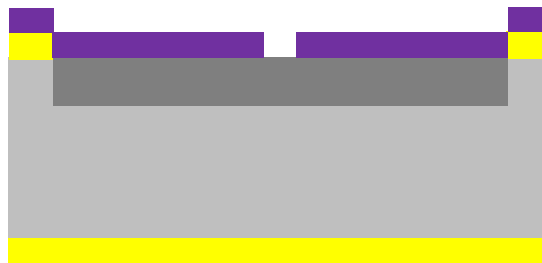
- Lithography



- ARC Etch



- Photo Resist removal



PV Fabrication Flow

Process Step

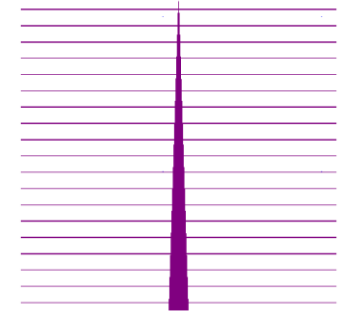
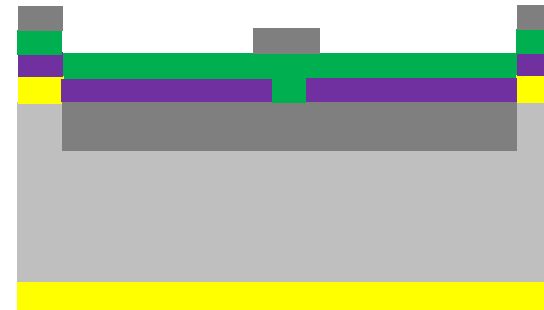
- Top Metal Deposition

Cross Section View

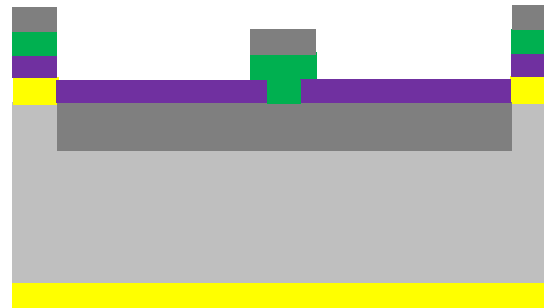


Top View/Mask

- Lithography



- Top Metal Etch

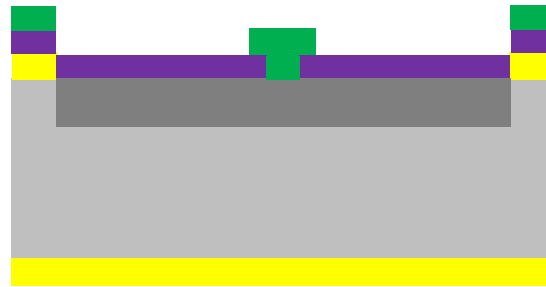


PV Fabrication Flow

Process Step

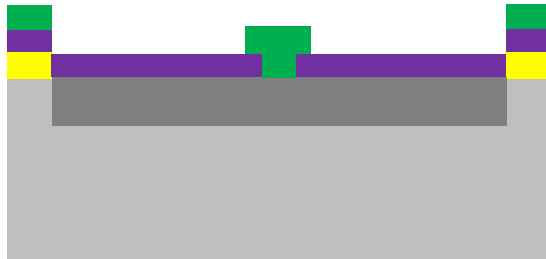
- Photo Resist removal

Cross Section View



Top View/Mask

- Back Oxide removal



- Back Metal deposition and anneal

